

Board to Board Connectors

Z-PACK J Series Interconnection System

Power Connector / 6-position

Receptacle

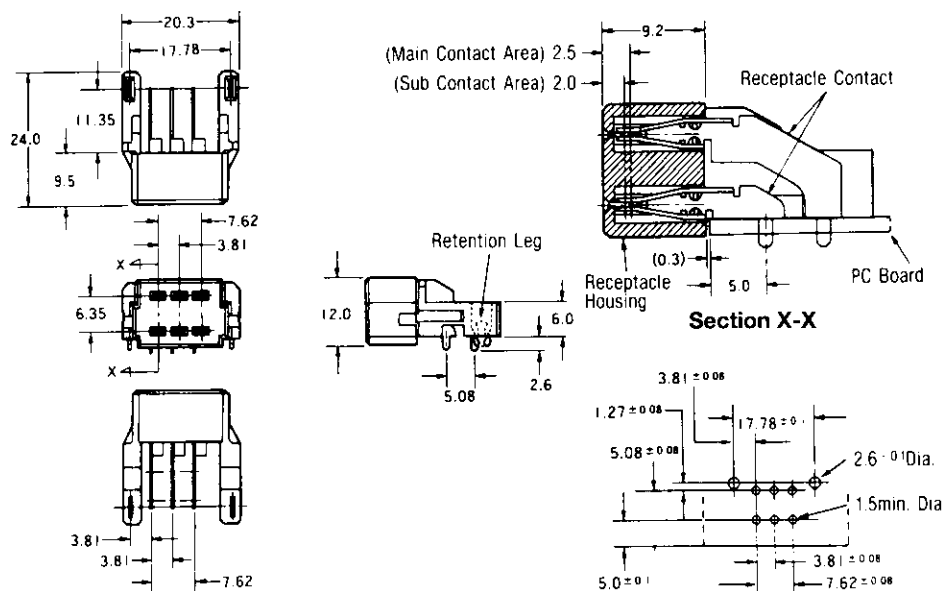
Material and Finish :

Housing — Liquid crystal polymer, black

Contact — Copper alloy
Nickel underplated to more than $1.27\mu\text{m}$ in thickness
Mating area : Gold plated (see table)

Tine section : Tin-lead plated or tin plated to more than $1.0\mu\text{m}$ in thickness

Retention leg — Tin-lead plated or tin plated to more than $1.0\mu\text{m}$ in thickness over nickel underplate of more than $1.27\mu\text{m}$ in thickness.



Recommended PC Board Layout

Part Number	Gold-plate thickness in mating area (Min.)	Recommended board thickness
179446-1	$0.5\mu\text{m}$	1.6 ± 0.2

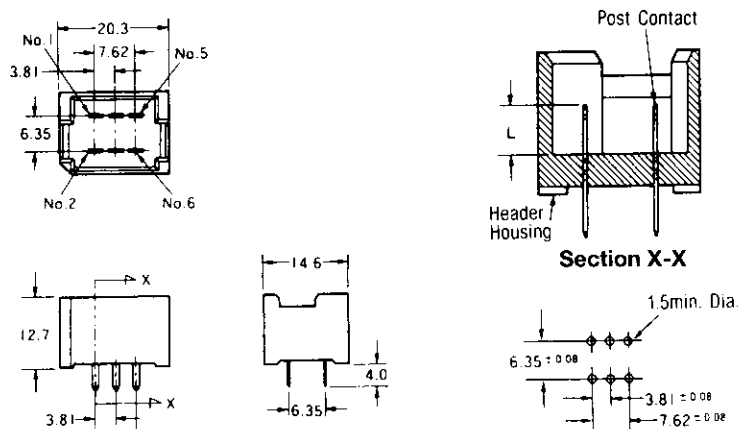
Header

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Recommended PC Board Layout

Part Number	Post length L	Circuit Number	Gold-plate thickness in mating area	Recommended board thickness
1-179447-1*	5.9	2, 3, 4, 5	$0.5\mu\text{m}$	3.0 ± 0.2
	6.5	1, 6		

*Housing color : natural.